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MIRTEC to Display Its State-of-the-Art 3D AOI and SPI Systems at SMTA International 2026

September 2026 – MIRTEC, the 'Global Leader in Inspection Technology,' is pleased to announce its participation in the SMTA International 2026, taking place October 27-29 at Donald E. Stephens Convention Center in Rosemont, IL. During the event, MIRTEC will showcase advanced 3D Automated Optical Inspection (AOI), Solder Paste Inspection (SPI), and Smart Factory Automation solutions, specifically designed to meet the demanding inspection requirements of the electronics manufacturing industry. Attendees are invited to visit MIRTEC's booth #2929 and experience firsthand the company's commitment to innovation, quality, and productivity.

Key Inspection Systems on Display:

Anti-Reflection Technology (ART)

MIRTEC's Anti-Reflection Technology (ART) 3D AOI System is the first 95MP Multi-Camera/Full HD Projection inspection platform. Equipped with five high-resolution cameras and four full HD digital projectors, the system delivers unprecedented accuracy for inspecting highly reflective objects such as solder joints, an area where conventional AOI systems struggle. The breakthrough lies in ART's innovative optical architecture. Conventional AOI solutions often rely on algorithms to fill in data lost due to specular reflections or blind spots caused by component structures. ART resolves these limitations by capturing 3D data from multiple directions, ensuring that solder joints are inspected entirely on the basis of actual measured data. Even when reflections or blind spots prevent the top-down camera from capturing accurate results, ART's side cameras fill in the gaps, enabling comprehensive inspection without compromise.



MV-6 OMNI

The MV-6 OMNI combines MIRTEC's exclusive OMNI-VISION 3D AOI technology with its 12-projection blue-light moiré system and 8-phase coaxial color lighting provide precise 3D measurement across diverse PCB conditions. AI auto teaching, dedicated THT algorithms, optional 45mm Z-axis inspection, 18MP side cameras, and an internal flipper expand coverage for tall components, side features, OCR, and double-sided PCBs.

MS-11

The MS-11 is a premium 3D SPI system designed for stable, high-precision solder paste inspection. Its 25MP camera, large FOV, and telecentric lens improve measurement consistency while reducing inspection time. The optional Solder Supplement Function automatically corrects insufficient or missing solder to reduce defects and improve process efficiency.

Commitment to Smart Manufacturing

"MIRTEC remains committed to helping electronics manufacturers achieve higher quality, greater productivity, and more intelligent production through advanced AOI, SPI, and Smart Factory technologies," said Brian D' Amico, President, MIRTEC Corp. "We look forward to meeting customers and partners at Booth #2929 and demonstrating how MIRTEC's AI-driven inspection and process solutions can support real-world manufacturing challenges."

MIRTEC is a leading global supplier of automated inspection systems for the electronics manufacturing industry. For more information about MIRTEC's innovative inspection solutions and their participation in SMTA International 2026, please visit www.mirtec.com.